

17th European Wet Users Meeting

Thursday, November 30, 2023, 14:00 – 18:00

Dorint Hotel, Chemnitz, Germany

Organized by the European CMP&WET Usersgroup

Agenda

- 13:00 Welcome coffee, tea, softdrinks
- 14:00 Opening Remarks
Knut Gottfried
Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany
- Wet Processes: Session 1**
Session Chair: Gerfried Zwicker, zwickerconsult, Berlin, Germany
- 14:15 L: Debottlenecking of Wastewater Treatment Systems – How to Make Money out of Waste
Jochen Ruth
Pall Microelectronics, Dreieich, Germany
- 14:40 L: High Efficiency Cleaning for Permanent Bonding-Based 3D Applications
Don Dussault
Prosys, Campbell, CA, USA
- 15:05 L: Advanced DI-Water Heating with Recirculation Flow
Nick Rose
Trevor
- 15:30 **Coffee Break**
- Wet Processes: Session 2**
Session Chair: Don Dussault, Prosys, Campbell, CA, USA
- 16:10 L: Electrochemical Deposition of Metallic Indium
Conrad Guhl
Fraunhofer IPMS-CNT, Dresden, Germany
- 16:35 L: Silicon-Direct Galvanic
Mike Becker
NBTechnology, Bremen, Germany
- 17:00 L: Investigation of Cleaning Alternatives post-CMP with Ceria Slurry
Teresa Weber
Infineon Technologies, Dresden Germany
- 17:25 End of Wet Users Meeting / time for networking and discussion
- 19:00 Workshop Dinner, Dorint Hotel

46th European CMP Users Meeting

Friday, December 1, 2023, 9:00 – 13:00

Dorint Hotel, Chemnitz, Germany

Organized by the European CMP&WET Usersgroup

Agenda

8:30 Welcome coffee, tea, softdrinks

9:00 Opening Remarks
Gerfried Zwicker
zwickerconsult, Berlin, Germany

Tutorial

Session Chair: Martin Kulawski, Advaplan, Espoo, Finland

9:05 L: Tungsten CMP Application Tutorial
Federico Barbieri
CMC Materials, Entegris, Barry, United Kingdom

CMP Processes: Session 1

Session Chair: Martin Kulawski, Advaplan, Espoo, Finland

9:40 L: Methods for CMP Process Variation Reduction Using Precision Engineered Pad Conditioner
Walter Schönhofen
3M Deutschland, Neuss, Germany

10:05 S: Ebara Readiness for SiC CMP
Kenrei Tei
Ebara Corp., Fujisawa, Japan

10:20 S: Opening of the Backside of ICs for Failure Analysis Using CMP
¹ Gerfried Zwicker, ² Christian Boit, ³ Awwal Adesunkanmi, ³ Norbert Herfurth
¹ zwickerconsult, Berlin, ² TU-Berlin, ³ IHP, Frankfurt/O, Germany

10:35 **Coffee Break**

CMP Processes: Session 2

Session Chair: Benjamin Steible, Fraunhofer ISIT, Itzehoe, Germany

11:15 L: Acting as Detective: Investigating the Origin of a Specific Defect in poly-CMP
Peter Seidel
Infineon Technologies, Dresden, Germany

11:40 L: Subsurface Damage Characterization Using Surface Photovoltage Spectroscopy
Imme Ellebrecht
ErzM-Technologies, Chemnitz, Germany

- 12:05 L: Slurry Particle Size Distribution In-Line Measurement
Rashid Mavliev
Mavlipa LLC, Santa Clara, CA, USA
- 12:30 L: Smooth Wafer Surfaces for Dynamic Bragg Reflectors – How Reliable and Meaningful Are RMS Parameters?
Conrad Guhl
Fraunhofer IPMS-CNT, Dresden, Germany
- 12:55 S: Some Highlights from ICPT 2023 in Kanazawa, Japan
Gerfried Zwicker
zwickerconsult, Berlin, Germany
- 13:10 Final remarks
- 13:20 Sandwiches, snacks, tea, coffee, time for discussion
- 14:00 End of CMP Users Meeting